

# **SPECIFICATION**

## **Character Type STN Dot Matrix LCD Module**

JM320240C

SHENZHEN JINGHUA DISPLAYS CO.,LTD

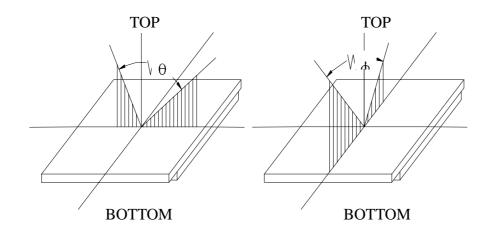


# GENERAL SPECIFICATION 320 X 240 dot display Samsung LCD driver: S6B2086X01 Interface with 8-bit MPU (directly connected to Z80 serial MPU) **Display Specification** Display Mode: graphic, text and combination text-graphic mode Display Dot: 320 X 240 Display type: FSTN Display color-Display background color: White Polarizer mode:Positive. Transflective. Viewing angle: 9:00 Display duty: 1/240 Driving bias: 1/16 Memory and External Memory: A standard 160-word character generator ROM 64K external display RAM (static RAM) Mechanical characteristics (Unit:mm) Extenal dimension: 166\*109\*13.1 View area: 122.0\*92.0 Dot size: 0.33\*0.33 Dot pitch: 0.36\*0.36 POWER: negative power;+5V power



#### • Optical Characteristics

(1) Definition of viewing Angle



(2) Definition of Contrast Ratio:

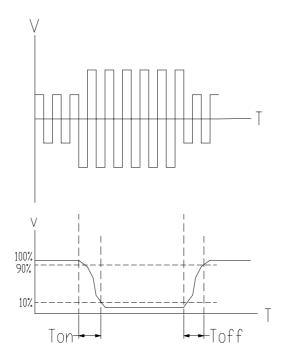
Contract Datio	Reflectance value of non-selected state brightness	
Contrast Ratio =	Reflectance value of selected state brightness	Test condition :

standard A light source

(3) Response Time

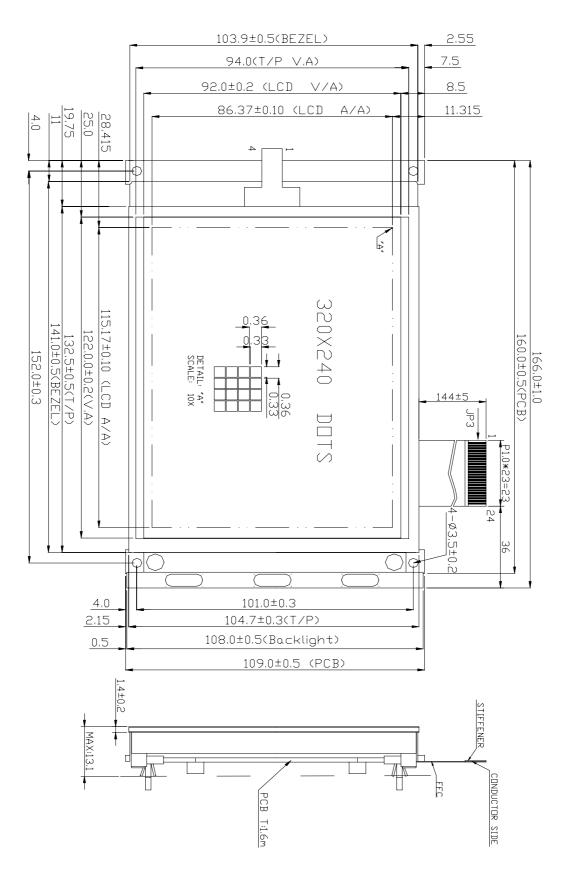
Response time is measured as the shortest period of time possible between the change

in state of an LCD segment as demonstrated below



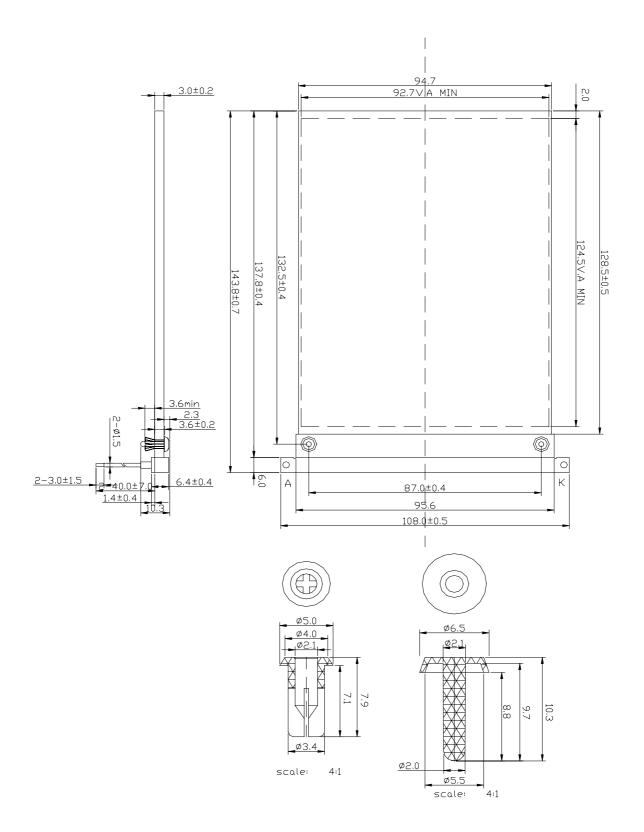


#### • External Dimension(For LED backlight and touch panel)



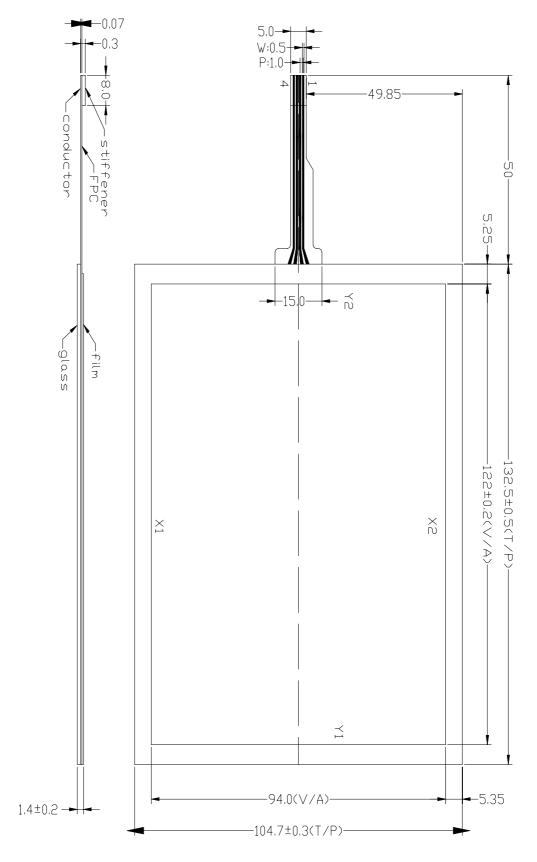


• External Dimension(For LED backlight)





#### • TOUCH PANEL





#### • LED Backlight

## Electrical/Optical Specifications:

	Symbol	Min.	Тур.	Max.	Unit	Conditions
Forward Voltage	Vf	-	4.0	-	V	
Forward Current	If	-	90	120	mA	Vf=4.0V
Power Dissipation	Pd	-	0.36	-	W	Vf=4.0V
Reverse Vollage	Vr	-	5.0	-	V	
Reverse Current	Ir	-	1.2	-	mA	
Luminous Intensity	Iv	-	160.0	-	Cd/m2	
Luminous Uniformity	-	70	-	-	%	Vf=4.0V
Chromaticity Coordinate	-	X=0.298 Y=0.305	-	X=0.328 Y=0.335	-	
Emission Wavclength	λp	-	-	-	nm	If=15mA
Spectral Range	$\Delta \lambda$	-	-	-	nm	Ta=25℃ Each Chip

#### Absolute Maximum Ratings At Ta=25°C

Parameter	Symbol	Specification.	Unit	Remark
Power Dissipation	Pad	360	mW	
Forward Current	Iaf	90	mA	
Reverse Voltage	Vr	5	V	
Operating Temperature	Topr	-30 ℃ TO +85 ℃	°C	
Storage Temperature	Tstg	-40°℃ TO +100°C	°C	

#### Electrical/Optical Characteristics At Ta=25 °C

Parameter	Symbol	Min.	Тур.	Max.	Unit	Remark
Average Luminous Intensity	Iv	150	160		cd/m <sup>2</sup>	Vf=4.0V
Luminous Intensity	-	70	-	-	%	
	Х	0.29	0.3	0.31	-	
Chrornaticity Coordinate	Y	0.26	0.3	0.33	-	Vf=4.0V
Forward Voltage	Vf	-	4.0	-	V	
Reverse Current	Ir	-	1.2	-	mA	



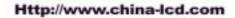
• Absolute Maximum	Kaungs					
ITEM	Symbol	Min	Туре	Max	Unit	
Oprating temperature	Тор	0	-	+50	°C	
Storage temperature	Tst	-20	-	+70	°C	
Input Voltage	Vi	-0.3	-	Vdd+0.3	V	
Supply voltage for Logic	Vdd-Vss	-0.3	-	+7.0	V	
Supply voltage for LCD	Vdd-V0	-0.3	-	+30.0	V	
Static electricity	Be sure that you are grounded when handing LCM					

#### • Absolute Maximum Ratings

## • Electrical Characteristics (Ta=25°C, Vdd= 5.0V)

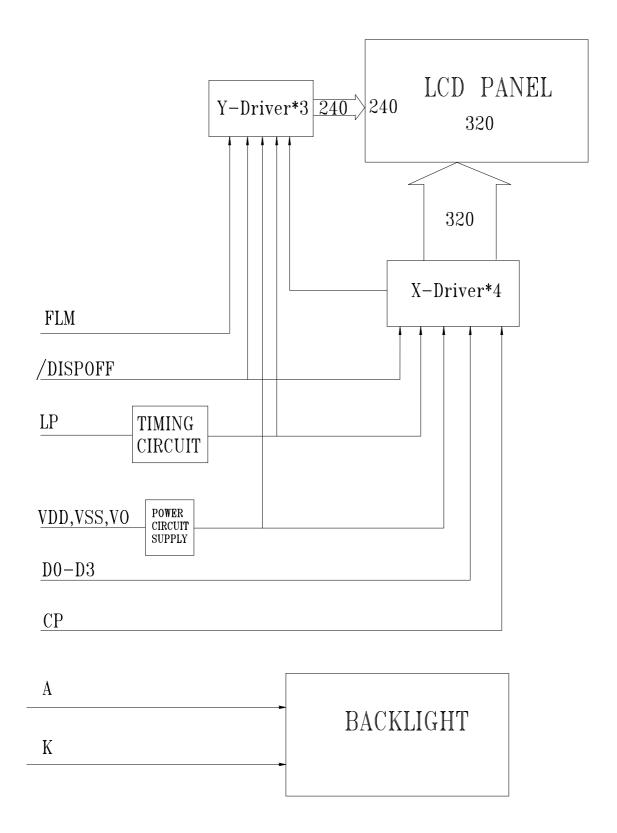
Item	Symbol	Condition	Sta	ue	Unit	
пеш	Symbol	Condition	min	Туре	max	Unit
Supply Voltage for logic	Vdd-Vss	-	2.7	5.0	5.5	V
Supply Voltage for LCD	Vdd-V0	-	-	24.0	-	V
Input high voltage	Vih	-	0.8Vdd	-	Vdd	V
Input low voltage	Vil	-	-	-	0.2Vdd	V
Output high voltage	Vo <sub>h</sub>	Ioh=0.4mA	Vdd-0.4	-	-	V
Output high voltage	$V_{ol}$	Iol=0.4mA	-	-	0.4	V
Supply Current for logic	*Idd	-	-	6	10	mA
Frame frequency	FLM	-	35	-	150	Hz
M signal frequency	Fm	-	35	-	150	Hz

\*Idd Measurement condition is for all pixels on display.



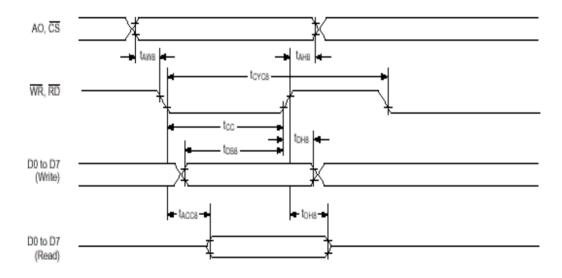


#### • Block Diagram





#### • 8080 family interface timing



#### Ta = -20 to $75^{\circ}C$

Gianal	Symbol	Parameter	VDD = 4.	5 to 5.5V	VDD = 2.7	7 to 4.5V	Unit	Condition
Signal	Symbol	Faranieter	min	max	min	max	Unit	Condition
A0, CS	tah8	Address hold time	10		10	Ι	ns	
A0, 03	tAW8	Address setup time	0	Ι	0	Ι	ns	
WR, RD	tCYC8	System cycle time	See note.	Ι	See note.	Ι	ns	
WR, RD	tcc	Strobe pulsewidth	120	Ι	150	Ι	ns	CL = 100pF
	tDS8	Data setup time	120		120	Ι	ns	
D0 to D7	tDH8	Data hold time	5	Ι	5	Ι	ns	
tACC8		RD access time	-	50	-	80	ns	
	ton8	Output disable time	10	50	10	55	ns	

Note: For memory control and system control commands:

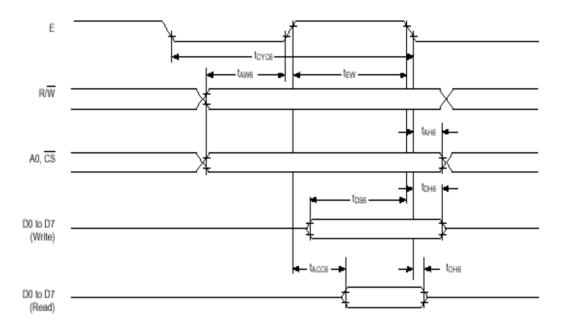
tCYC8 = 2tc + tCC + tCEA + 75 > tACV + 245

For all other commands:

toycs = 4tc + toc + 30



#### • 6800 family interface timing



Note: toyos indicates the interval during which CS is LOW and E is HIGH.

#### Ta = −20 to 75°C

Signal	Symbol	Parameter	VDD = 4.5 to		VDD = 2.7	7 to 4.5V	Unit	Condition	
Signal	Symbol	Farameter	min	max	min	max	Unit	Condition	
A0,	tCYC6	System cycle time	See note.	_	See note.	Ι	ns		
A0, CS,	tAW6	Address setup time	0	_	10	Ι	ns		
R/W	tAH6	Address hold time	0	_	0	-	ns		
	tDS6	Data setup time	100	_	120	Ι	ns	CL =	
D0 to D7	tDH6	Data hold time	0	_	0	Ι	ns	100 pF	
001007	ton6	Output disable time	10	50	10	75	ns		
tACC6		Access time		85		130	ns		
E	tEW	Enable pulsewidth	120	_	150	-	ns		

Note: For memory control and system control commands:

tcyce = 2tc + tew + tcea + 75 > tacv + 245

For all other commands:

t<sub>CYC6</sub> = 4t<sub>C</sub> + t<sub>EW</sub> + 30



#### • AC CHARACTERISTICS

(1) SEGMENT DRIVER APPLICATION

(Vss = 0 V, Ta = -30 ~ +85°C)

Characteristic	Symbol	Test	(1) VI	<b>DD=5 V</b> ±	10%	(2) VI	DD=3 V ±	10%	Unit
Characteristic	Symbol	Condition	MIN	TYP	MAX	MIN	TYP	MAX	Unit
Clock cycle time	t <sub>CY</sub>	Duty=50%	125	-	-	250	-	-	
Clock pulse width	t <sub>WCK</sub>	-	45	-	-	95	-	-	
Clock rise/fall time	t <sub>R/tF</sub>	-	-	-	-	-	-	30	
Data set-up time	t <sub>DS</sub>	-	30	-	-	65	-	-	
Data hold time	t <sub>DH</sub>	-	30	-	-	65	-	-	
Clock set-up time	t <sub>CS</sub>	-	80	-	-	120	-	-	ns
Clock hold time	t <sub>CH</sub>	-	80	-	-	120	-	-	
Propagation delay time	t <sub>PHL</sub>	ELB Output		-	60		_	125	
Propagation delay time		ERB Output	•	-	60	-	-	125	
ELB,ERB set-up time	toou	ELB Input	30		65				
	t₽SU	ERB Input	30	-	-	65		-	
DISPOFFB low pulse width	t <sub>WDL</sub>	-	1.2	-	-	1.2	-	-	μs
DISPOFFB clear time	t <sub>CD</sub>		100	-	-	100	-		ns
M - OUT propagation delay time	t <sub>PD1</sub>		-	-	1.0	-	-	1.2	
CL1 - OUT propagation delay time	t <sub>PD2</sub>	CL=15 pF		-	1.0	-	-	1.2	μs
DISPOFFB - OUT propa- gation delay time	t <sub>PD3</sub>			-	1.0	-	-	-	



## • AC CHARACTERISTICS(CONTINUED)

## (2) COMMON DRIVER APPLICATION

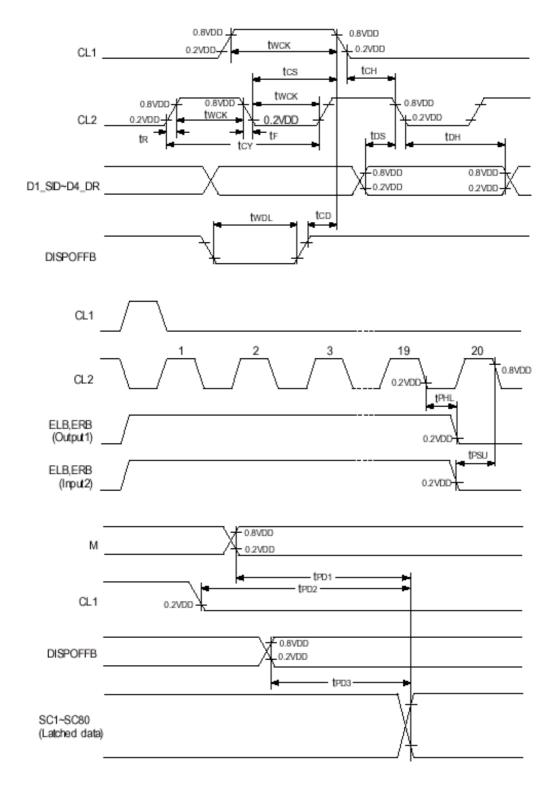
(Vss = 0 V, Ta = -30 ~ +85°C)

Characteristic	Symbol	Test	(1) VI	DD=5 V ±	10%	(2) VDD=3V±10%			Unit
Characteristic	Symbol	Condition	MIN	TYP	MAX	MIN	TYP	MAX	Unit
Clock cycle time	t <sub>CY</sub>	Duty=50%	250	-	•	500		•	
Clock pulse width	t <sub>WCK</sub>	-	45	-		95			
Clock rise/fall time	t <sub>R/tF</sub>	-	-	-	50	-	-	50	ns
Data set-up time	t <sub>DS</sub>		30	-		65			
Data hold time	t <sub>DH</sub>		30	-		65			
DISPOFFB low pulse width	$t_{WDL}$		1.2	-		1.2			μs
DISPOFFB clear time	tco		100	-		100			00
Output delay time	t <sub>DL</sub>		-	-	200			250	ns
M - OUT propagation delay time	t <sub>PD1</sub>				1.0			1.2	
CL1 - OUT propagation delay time	t <sub>PD2</sub>	CL=15 pF			1.0			1.2	μs
DISPOFFB - OUT propagation delay time	t <sub>PD3</sub>				1.0			1.2	



#### • AC CHARACTERISTICS(CONTINUED)

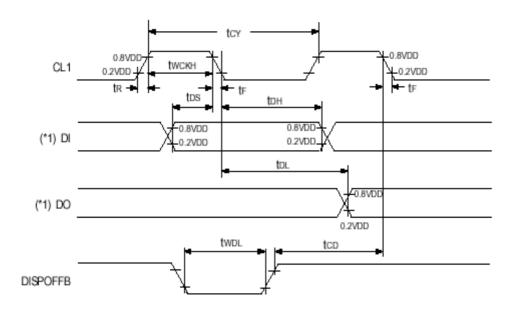
(3) SEGMENT DRIVER APPLICATION TIMING



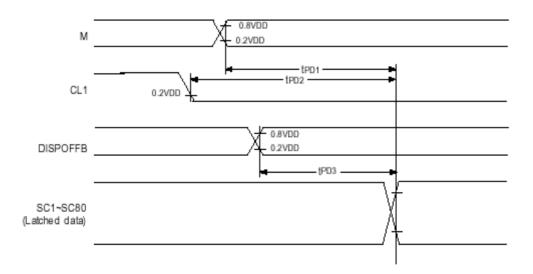


#### • AC CHARACTERISTICS(CONTINUED)

(4) COMMON DRIVER APPLICATION TIMING



(\*1) When in single-type interface mode  $DI \Rightarrow D2\_DL(SHL="L"), D4\_DR(SHL="H")$   $DO \Rightarrow D4\_DR(SHL="L"), D2\_DL(SHL="H")$ When in dual-type interface mode  $DI \Rightarrow D2\_DL$  and  $D3\_DM(SHL="L"), D4\_DR$  and  $D3\_DM(SHL="H")$  $DO \Rightarrow D4\_DR(SHL="L"), D2\_DL(SHL="H")$ 

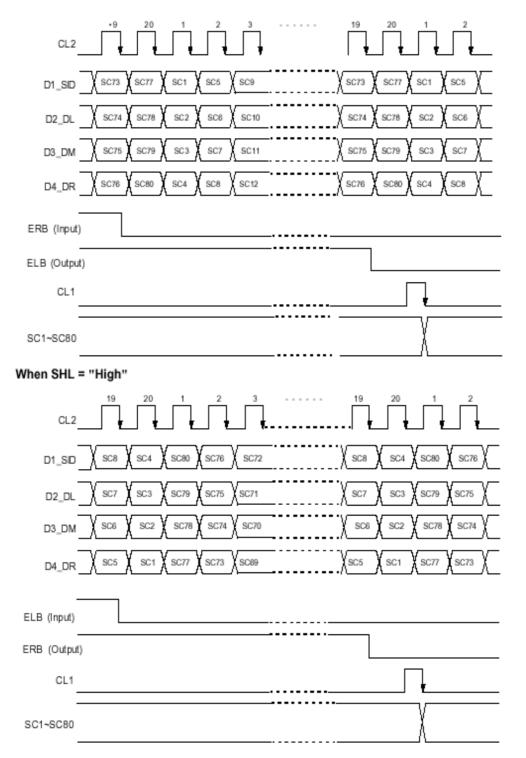




#### • OPERATION TIMING DIAGRAM

4-BIT PARALLEL MODE INTERFACE SEGMENT DRIVER

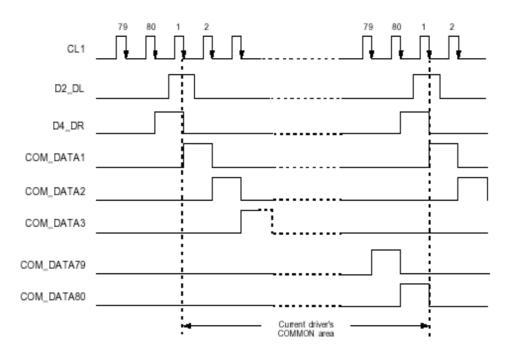
#### When SHL = "Low"



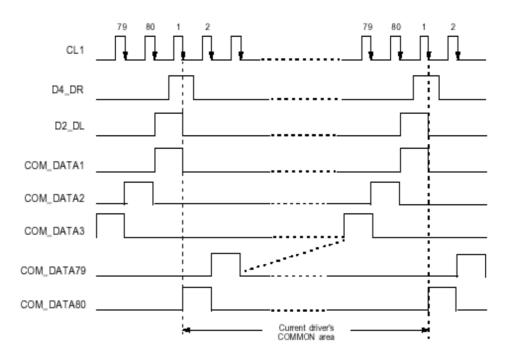


#### SINGLE-TYPE INTERFACE MODE COMMON DRIVER

#### When SHL = "Low"









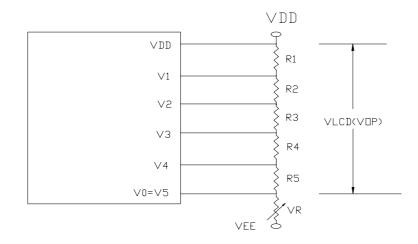
## • Pin assignment

#### **JP3:**

Pin NO.	Symbol	Function	I/O
1	D0		I/O
2	D1		I/O
3	D2	Data Bus	I/O
4	D3		I/O
5	/DISPOFF	H:ON L:OFF	Ι
6	FLM	First LINE MARKER	Ι
7	NC	/	/
8	LP	LATCH PULSE	
9	СР	DATA SHIFT2	Ι
10	VDD	POWER SUUPLY FOR LOGIC	Р
11	VSS	GND	Р
12	VEE	POWER SUUPLY FOR LCD	Р
13	V0	OPERATING VOLTAGE LCD DRIVING	
14	FG	FRAME GROUND	
15	X1	TOUCH PANEL LOW SIGNAL IN Y AXIS	I/O
16	X2	TOUCH PANEL UPPER SIGNAL IN Y AXIS	I/O
17	Y1	TOUCH PANEL RIGHT SIGNAL IN X AXIS	I/O
18	Y2	TOUCH PANEL LEFT SIGNAL IN X AXIS	I/O
19	NC	/	/
20	А	ANODE of LED UNIT	/
21	K	CATHODE of LED UNIT	/
22	NC	/	/
23	NC	/	/
24	NC	/	/

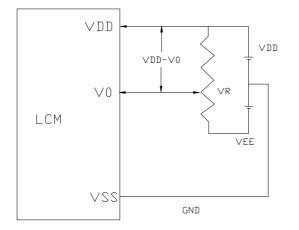


### • LCD Driving Source(1/16 Bias)



- V1=Vdd 1/16Vlcd
- V2= Vdd 2/16Vlcd
- V3=Vdd 14/16Vlcd
- V4= Vdd 15/16Vlcd
- V5= Vdd Vlcd

Dual Supply Voltage Types



Vdd-V0: LCD Driving Voltage



## Quality Units

#### 1.Quality level

- 1.1 Inspection conditions
  - 1.1.1The environmental conditions for inspection shall be as follows

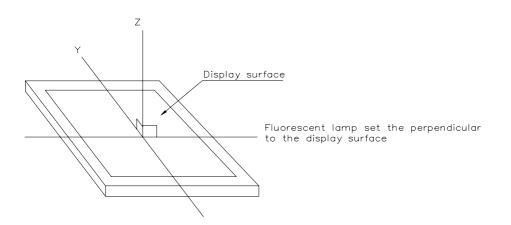
Room temperature: 22±5 °C

Humidity : 65±20%RH

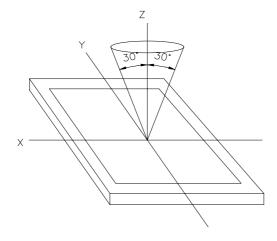
1.1.2 The external visual inspection

The inspection shall be performed by using a single 20W fluorescent lamp for illumination and the distance from LCD to eyes of the inspector should be 30±5cm.

1.1.3 Light method



1.1.4 Inspection distance and angle





Inspection should be performed within  $\Phi(\Phi$  is usually 30°) from Z axis to each X and Y axis.

Inspection distance of any direction within  $\Phi$  must be kept 30±5cm to the display surface.

1.2 Sampling procedures for each item's acceptance level table

Defect type	ct type Sampling procedures	
Major defect	0.65	
Major defectnormal inspection.Minor defectGB2828-87 single sampling plans fo normal inspection.		1.5

- 1.3 Classification of defects
  - 1.3.1 Major defect

A major defect refers to a defect that is considered to substantially degrade usability for product applications.

1.3.2 Minor defect

A minor defect refers to a defect that is not considered to substantially degrade product application, or a defect that deviates from existing standards almost unrelated to the effective use of the product or its operation

- 2. Nonconforming Analysis and Deal With Manner
  - 2.1 Nocconforming analysis
  - (1)Customer should supply the detail data of nonconforming sample and the non-suitable sample.

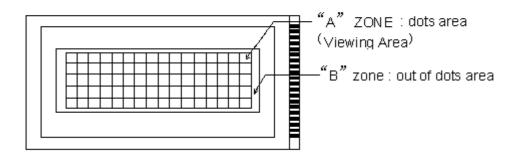
(2)After accepting detail data non-suitable sample from customer, the analysis of nonconforming should be finished in two weeks.

- 2.2 Deal with nonconforming
  - (1)Both supplier and customer should analyze the reason together and discuss the disposition of nonconforming when the reason of



nonconforming is not sure.

- 3. Standard of The Product Appearance Test
  - 3.1 manner of appearance test
  - (1)The test must be under 20w\*2 or 40w fluorescent light ,and the distance of view must be at 30 cm.
  - (2)When test the model of transmissive product must add the reflective plate.
  - (3)The test direction is base on about around 45° of vertical line.
  - (4)Definition of area:



A area: dots area.

B area: out of dots area.(outside dots area)

- 3.2 basic principle:
- (1) it will accord to the AQL when the standard can not be described.
- (2)the sample of the lowest acceptable quality level must be discussed by both supplier and customer when any dispute happened.
- (3)must add new item on time when it is necessary.
- 3.3 standard of inspection (unit:mm)



NO	ltms		Crite	erion of de	efects			AQL
01	Electrical te	sting	No I Curr spec LCE Mixe	Display,Di rent cor cifications	angle defe t types;	unction; excee		Major
02	Black or where the spots on LCD(displation of the spots) by the spot of the sp		,no pres	more tha sent.	an three w	vhite or	y 0.25mm black spots within 3mm.	Minor
	LCD black or white spo	ots.		A+B)/2	Size D(mi		Acceptable number	
	(non-display	/)		B 	D≤0.15		Ignore	
03	contamination (non-display		Ā	$\square$	0.15 D≤	ấ0.20	3	Minor
		,			0.20 D≤	<di>0.25</di>	2	
					0.25 D≤	<b>€0.30</b>	1	
	Dark lines			Width (m	ım)	Length (mm)	Acceptabl e number	
	and			W≤0.03	}	L≤3.0	3	
04	scratches		. <b>¥</b> w	0.03 W	/≤0.05	L≤2.0	2	Minor
		→ L	′ <b>≜</b>	0.05 W	/≤0.08	L≤2.0	1	
		L		0.08 W	/ ≤0.1	L≤3.0	0	
				0.1 W		L>3.0	0	
		Size D	) (mn	n)		Accept	table number	
	hubble in	D≤0.2	20			Ignore		
05	bubble in polarizer	0.20	D ≤ (	0.40			3	Minor
		0.40	D ≤ (	0.60			2	
		0.60	D				0	



		(1)Dot type	
06	Display Pattern		Minor
		Unit: mm $(A+B)/2 \le 0.25$ $C \ge 0$ $(D+E)/2 \le 0.25$ $(F+G)/2 \le 0.25$ Note: 1) Acceptable up to 3 damages. 2) If there're two or more pinholes per digit, it is rejected.	

07	Chip in corner	I.T.O b	electrode	W		Minor
		а	b	С	Acceptable number	
		a 4mm	b≤W	C≤T	3	



08	Chip in seal area		EWING AREA W	SEAL		Minor
		а	b	с	Acceptable number	
		a 3mm	b≤1.5mm	c ≤ 1/2T	3	
			table, if c is ss or the seal		an 50% of the maged.	
09	Chip in pad(1)	b		W		Minor
		а	b	С	Acceptable number	
		a≤2mm	b ≤ W/4	c≤T	ignore	
		a≤3mm	b ≤ W/4	c≤T	3	





10	Chip in pad(2)	W	C	X			Minor
		а	b		С	Acceptable number	
		a≤2mm	b ≤ W/3	C≮	≤T	ignore	
		a≤4mm	b ≤ W/2	C ≤	≤T	3	
11	Chip in other sides	a a ≤ 3mm	C b b≤1mm		b c≤T	Acceptable number ignore	Minor
		a≤4mm	b ≤ 1.5mm		c≤T	3	
12	Glass rest			1	/4W		Minor



13	Black light	<ol> <li>lumimation source flikers when it.</li> <li>Spots or scratches that apper when lit must be judged using LCD spot,lines and contamination standards.</li> <li>Backlight doesn't light or color is wrong.</li> <li>Colour and luminance of backlight isn't permission to exceed criterion that customer affirmed.</li> </ol>	0.65 1.5 0.65 0.65
14	PCB COB	<ol> <li>COB seal may not have pinholes larger than 0.2mm or contamination.</li> <li>COB seal surgace may not have pinholes through to the IC</li> <li>The height of the COB should not exceed the height indicated in the assembly diagram.</li> <li>There may not be more than 2mm of sealant outside the seal area on the PCB.And there should be no more than three places.</li> <li>No oxidation or contamination PCB terminals.</li> <li>Parts on PCB must be the same as on the production charactersitic chart.There should be no wrong parts,,,missing partsor excess parts.</li> <li>The jumper on the PCB should conform to the product characteristic chart.</li> <li>If solder gets on bezel tab pads, LED pad,zebra pad or screw hole pad,make sure it is smoothed down.</li> </ol>	Minor Minor Major Minor Major Minor Major
15	Soldering	<ol> <li>No unmelted solder paste may be present on the PCB.</li> <li>No cold solder joints, missing solder connections, oxidation or icile.</li> <li>No short circuits in components on PCB.</li> <li>No short cicuits in components on PCB.</li> </ol>	Minor Minor Minor Major
16	General appearance	<ol> <li>No oxidation,contamiation,curves or, bends on interface Pin or TCP.</li> <li>No cracks on interface pin of TCP.</li> <li>No contamination.solder residue or solder balls on product.</li> <li>The IC on the TCP may not be damaged, circuits.</li> </ol>	Minor Major Minor <b>Mino</b> r



5.	The uppermost dege of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever.	Minor
6,	The residual rosin or tin oil of sldering (component) is not burned into brown or black color.	Minor
7、	Sealant on top of the ITO circuit has not hardeed.	Minor
8、	Pin type must match type in specification sheet.	
9、	LCD pin loose or missing pins.	Major
10、	Product packaging must the same as specified on packaging specification sheet.	Major Major
11、	Product dimension and structure must conform to product specification sheet.	Major
12、	The appearance of Heat Seal should not admit any dirt and break.	Major

3、Standard specification for reliability of LCD Module

ITEM	Condition	Criterion
1)High	50℃	Total current consumption
temperature	24h	should be below double of
operating		initial value.
2)Low	-30℃	Cosmetic defects should not
temperature	8h	be happened.
operating		
3)Humidity(witho	40℃ 90%RH 240hours	
ut polarizer)		
4)High	60°C	
temperature	16hours	
storage		
5)Low	<b>-10</b> ℃	
temperature	8hours	
storage		
6)Thermal shock	-20°C → 25°C → 70°C → 25°C	
storage	30min 5min 30min	
	5min	
	5cycle	





7)Vibration (package state)	10 ~ 150Hz 5m/s <sup>2</sup>
	45min
8)Shock test (package state)	50Hz amplitude :0.7mm 30min for each direction (X.Y.Z)